

The SP5055 is a single chip frequency synthesiser designed for TV tuning systems. Control data is entered in the standard I<sup>2</sup>C BUS format. The device contains 4 addressable current limited outputs and 4 addressable Bi-Directional open collector ports one of which is a 3 bit ADC. The information on these ports can be read via the I<sup>2</sup>C BUS. The device has one fixed I<sup>2</sup>C BUS address and 3 programmable addresses, programmed by applying a specific input voltage to one of the current limited outputs. This enables 2 or more synthesisers to be used in a system.

### FEATURES

- Complete 2.6GHz Single Chip System
- Programmable via I<sup>2</sup>C BUS
- Low power consumption (5V 65mA)
- Low Radiation
- Phase Lock Detector
- Varactor Drive Amp Disable
- 6 Controllable Outputs, 4 Bi-Directional
- 5 Level ADC
- Variable I<sup>2</sup>C BUS Address For Multi Tuner Applications
- Full ESD Protection\*

\* Normal ESD handling procedures should be observed.

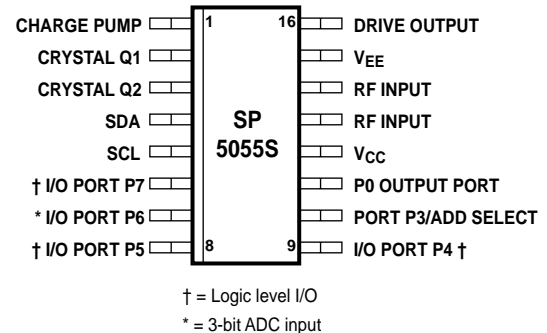
DS2361

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### Ordering Information

SP5055GS/KG/MPAS (Tubes)  
 SP5055GS/KG/MPAD (Tape & Reel)  
 16lead miniature plastic package



**MP16**

*Fig. 1 Pin connections – top view*

### APPLICATIONS

- Satellite TV
- High IF Cable Tuning Systems

## ELECTRICAL CHARACTERISTICS

$T_{amb} = -20^{\circ}\text{C}$  to  $+80^{\circ}\text{C}$ ,  $V_{CC} = +4.7\text{V}$  to  $5.3\text{V}$ .

These Characteristics are guaranteed by either production test or design. They apply within the specified ambient temperature and supply voltage unless otherwise stated. Reference frequency = 4MHz unless otherwise stated.

| Characteristic                         | Pin    | Value |           |         | Units             | Conditions  |
|--|--------|-------|-----------|---------|-------------------|---|
|  |        | Min.  | Typ.      | Max.    |                   |   |
| Supply current                         | 12     |       | 65        | 80      | mA                | $V_{CC} = 5\text{V}$  |
| Prescaler input voltage                | 13, 14 | 50    |           | 300     | mV <sub>RMS</sub> | 500MHz to 2.6GHz Sinewave   |
| Prescaler input voltage                | 13, 14 | 100   |           | 300     | mV <sub>RMS</sub> | 120MHz, see Fig. 5  |
| Prescaler input impedance              | 13, 14 |       | 50        |         | $\Omega$          |   |
| Prescaler input capacitance            |        |       | 2         |         | pF                |   |
| <b>SDA, SCL</b>                        |        |       |           |         |                   |   |
| Input high voltage                     | 4, 5   | 3     |           | 5.5     | V                 | Input voltage = $V_{CC}$<br>Input voltage = 0V<br>When $V_{CC} = 0\text{V}$   |
| Input low voltage                      | 4, 5   | 0     |           | 1.5     | V                 |   |
| Input high current                     | 4, 5   |       |           | 10      | $\mu\text{A}$     |   |
| Input low current                      | 4, 5   |       |           | -10     | $\mu\text{A}$     |   |
| Leakage current                        | 4, 5   |       |           | 10      | $\mu\text{A}$     |   |
| <b>SDA</b>                             |        |       |           |         |                   |   |
| Output voltage                         | 4      |       |           | 0.4     | V                 | $I_{\text{sink}} = 3\text{mA}$  |
| Charge pump current low                | 1      |       | $\pm 50$  |         | $\mu\text{A}$     | Byte 4, bit 2 = 0, pin 1 = 2V<br>Byte 4, bit 2 = 1, pin 1 = 2V<br>Byte 4, bit 4 = 1, pin 1 = 2V<br>$V_{\text{pin } 16} = 0.7\text{V}$ |
| Charge pump current high               | 1      |       | $\pm 170$ |         | $\mu\text{A}$     |   |
| Charge pump output leakage current     | 1      |       |           | $\pm 5$ | nA                |   |
| Charge pump drive output current       | 16     | 500   |           |         | $\mu\text{A}$     |   |
| Charge pump amplifier gain             |        |       | 6400      |         |                   |   |
| Recommended crystal series resistance  |        | 10    |           | 200     | $\Omega$          |   |
| Crystal oscillator drive level         | 2      |       | 80        |         | mVp-p             |   |
| Crystal oscillator negative resistance | 2      | 750   |           |         | $\Omega$          |   |
| <b>Output Ports</b>                    |        |       |           |         |                   |   |
| P0, P3 sink current                    | 10, 11 | 0.7   | 1         | 1.5     | mA                | $V_{\text{OUT}} = 12\text{V}$   |
| P0, P3 leakage current                 | 10, 11 |       |           | 10      | $\mu\text{A}$     | $V_{\text{OUT}} = 13.2\text{V}$   |
| P4-P7 sink current                     | 9-6    | 10    |           |         | mA                | $V_{\text{OUT}} = 0.7\text{V}$  |
| P4-P7 leakage current                  | 9-6    |       |           | 10      | $\mu\text{A}$     | $V_{\text{OUT}} = 13.2\text{V}$   |
| <b>Input Ports</b>                     |        |       |           |         |                   |   |
| P3 input current high                  | 10     |       |           | +10     | $\mu\text{A}$     | $V_{\text{pin } 10} = 13.2\text{V}$<br>$V_{\text{pin } 10} = 0\text{V}$   |
| P3 input current low                   | 10     |       |           | -10     | $\mu\text{A}$     |   |
| P4,P5,P7 input voltage low             | 9,8,6  |       |           | 0.8     | V                 | See Table 3 for ADC Levels  |
| P4,P5,P7 input voltage high            | 9,8,6  | 2.7   |           |         | V                 |   |
| P6 input current high                  | 7      |       |           | +10     | $\mu\text{A}$     |   |
| P6 input current low                   | 7      |       |           | -10     | $\mu\text{A}$     |   |

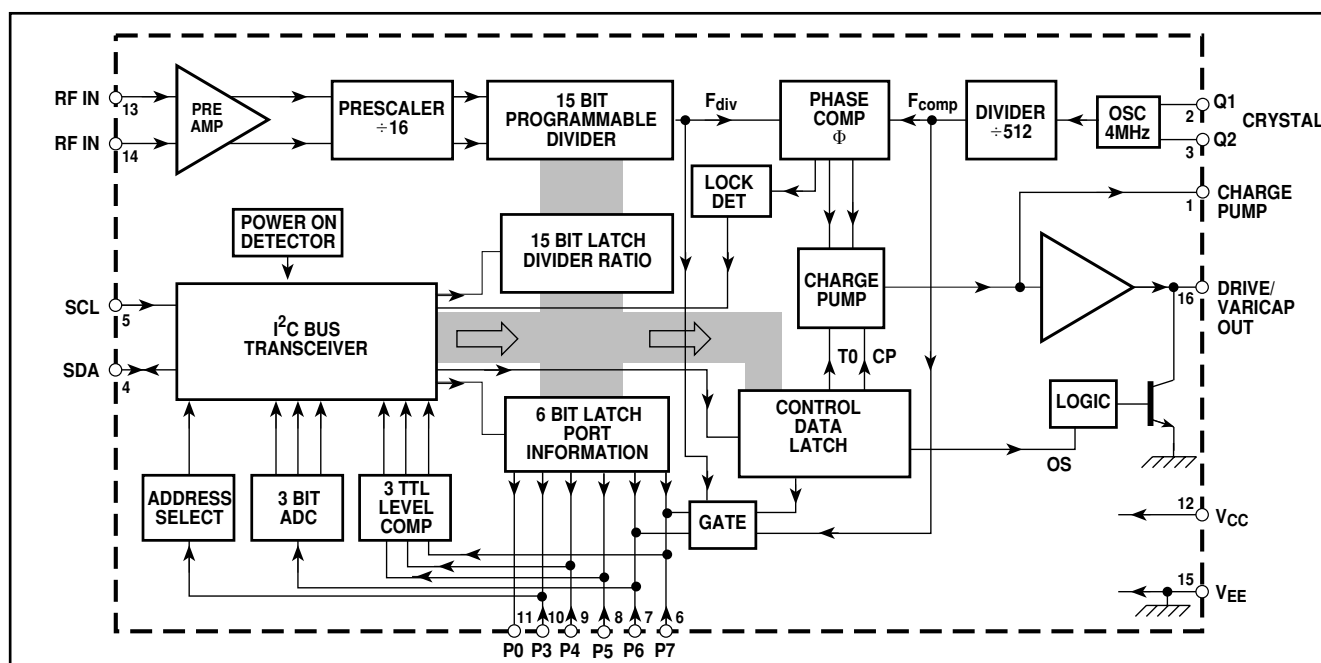


Fig. 2 Block diagram

## FUNCTIONAL DESCRIPTION

The SP5055 is programmed from an I<sup>2</sup>C BUS. Data and Clock are fed in on the SDA and SCL lines respectively as defined by the I<sup>2</sup>C BUS format. The synthesiser can either accept new data (write mode) or send data (read mode). The Tables in Fig. 3 illustrate the format of the data. The device can be programmed to respond to several addresses, which enables the use of more than one synthesiser in an I<sup>2</sup>C Bus system. Table 4 shows how the address is selected by applying a voltage to P3. The last bit of the address byte (R/W) sets the device into read mode if it is high and write mode if it is low. When the SP5055 receives a correct address byte it pulls the SDA line low during the acknowledge period and during following acknowledge periods after further data bytes are programmed. When the SP5055 is programmed into the read mode the controlling device accepting the data must pull down the SDA line during the following acknowledge period to read another status byte.

## WRITE MODE (FREQUENCY SYNTHESIS)

When the device is in the write mode Bytes 2 + 3 select the synthesised frequency while bytes 4 + 5 select the output port states and charge pump information.

Once the correct address is received and acknowledged, the first Bit of the next Byte determines whether that byte is interpreted as byte 2 or 4, a logic 0 for frequency information and a logic 1 for charge pump and output port information. Additional data bytes can be entered without the need to re-address the device until an I<sup>2</sup>C stop condition is recognised. This allows a smooth frequency sweep for fine tuning or AFC purposes.

If the transmission of data is stopped mid-byte (i.e., by another device on the bus) then the previously programmed byte is maintained.

Frequency data from bytes 2 and 3 is stored in a 15-bit shift register and is used to control the division ratio of the 15-bit programmable divider which is preceded by a divide-by-16 prescaler and amplifier to give excellent sensitivity at the local oscillator input; see Fig 5. The input impedance is shown in Fig 7.

The programmed frequency can be calculated by multiplying the programmed division ratio by 16 times the comparison frequency  $F_{comp}$ .

When frequency data is entered, the phase comparator, via the charge pump and varactor drive amplifier, adjusts the local oscillator control voltage until the output of the programmable divider is frequency and phase locked to the comparison frequency.

The reference frequency may be generated by an external source capacitively coupled into pin 2 or provided by an on-board 4MHz crystal controlled oscillator.

Note that the comparison frequency is 7.8125kHz when a 4MHz reference is used.

Bit 2 of byte 4 of the programming data (CP) controls the current in the charge pump circuit, a logic 1 for  $\pm 170\mu A$  and a logic 0 for  $\pm 50\mu A$ , allowing compensation for the variable tuning slope of the tuner and also to enable fast channel changes over the full band. Bit 4 of byte 4 (T0) disables the charge pump if set to a logic 1. Bit 8 of byte 4 (OS) switches the charge pump drive amplifier's output off when it is set to a logic 1. Bit 3 of Byte 4 (T1) selects a test mode where the phase comparator inputs are available on P6 and P7, a logic 1 connects  $F_{comp}$  to P6 and  $F_{div}$  to P7.

Byte 5 programs the output ports P0 to P7; on a logic 0 for a high impedance output, logic 1 for low impedance (on).

## READ MODE

When the device is in the read mode the status data read from the device on the SDA line takes the form shown in Table 2.

Bit 1 (POR) is the power-on reset indicator and is set to a logic 1 if the power supply to the device has dropped below 3V and the programmed information lost (e.g., when the device is initially turned on). The POR is set to 0 when the read sequence is terminated by a stop command. The outputs are all set to high impedance when the device is initially powered up. Bit 2 (FL) indicates whether the device is phase locked, a logic 1 is present if the device is locked and a logic 0 if the device is unlocked.

Bits 3, 4 and 5 (I2,I1,I0) show the status of the I/O Ports P7, P5 and P4 respectively. A logic 0 indicates a low level and a logic 1 a high level. If the ports are to be used as inputs they should be programmed to a high impedance state (logic 1). These inputs will then respond to data complying with TTL type voltage levels. Bits 6, 7 and 8 (A2,A1,A0) combine to give the output of the 5 level ADC.

The 5 level ADC can be used to feed AFC information to the microprocessor from the IF section of the receiver, as illustrated in the typical application circuit.

## APPLICATION

A typical Application is shown in Fig. 4. All input/output interface circuits are shown in Fig. 6.

|                                  | MSB            |                 |                 |                 |                 | LSB             |                |                |   |               |
|----------------------------------|----------------|-----------------|-----------------|-----------------|-----------------|-----------------|----------------|----------------|---|---------------|
| <b>Address</b>                   | 1              | 1               | 0               | 0               | 0               | MA1             | MA0            | 0              | A | <b>Byte 1</b> |
| <b>Programmable divider</b>      | 0              | 2 <sup>14</sup> | 2 <sup>13</sup> | 2 <sup>12</sup> | 2 <sup>11</sup> | 2 <sup>10</sup> | 2 <sup>9</sup> | 2 <sup>8</sup> | A | <b>Byte 2</b> |
| <b>Programmable divider</b>      | 2 <sup>7</sup> | 2 <sup>6</sup>  | 2 <sup>5</sup>  | 2 <sup>4</sup>  | 2 <sup>3</sup>  | 2 <sup>2</sup>  | 2 <sup>1</sup> | 2 <sup>0</sup> | A | <b>Byte 3</b> |
| <b>Charge pump and test bits</b> | 1              | CP              | T1              | T0              | 1               | 1               | 1              | OS             | A | <b>Byte 4</b> |
| <b>I/O port control bits</b>     | P7             | P6              | P5              | P4              | P3              | X               | X              | P0             | A | <b>Byte 5</b> |

Table 1 Write data format (MSB transmitted first)

|                    |     |    |    |    |    |     |     |    |   |               |
|--------------------|-----|----|----|----|----|-----|-----|----|---|---------------|
| <b>Address</b>     | 1   | 1  | 0  | 0  | 0  | MA1 | MA0 | 1  | A | <b>Byte 1</b> |
| <b>Status byte</b> | POR | FL | I2 | I1 | I0 | A2  | A1  | A0 | A | <b>Byte 2</b> |

Table 2 Read data format (MSB is transmitted first)

|                               |  |
|-------------------------------|--|
| <b>A</b>                      | : Acknowledge bit  |
| <b>MA1, MA0</b>               | : Variable address bits (see Table 4)                        |
| <b>CP</b>                     | : Charge Pump current select                                 |
| <b>T1</b>                     | : Test mode selection  |
| <b>T0</b>                     | : Charge pump disable  |
| <b>OS</b>                     | : Varactor drive Output disable Switch                       |
| <b>P7, P6, P5, P4, P3, P0</b> | : Control output states                                      |
| <b>POR</b>                    | : Power On Reset indicator                                   |
| <b>FL</b>                     | : Phase lock detect flag                                     |
| <b>I2, I1, I0</b>             | : Digital information from Ports P7, P5 and P4, respectively |
| <b>A2, A1, A0</b>             | : 5 Level ADC data from P6 (see Table 3)                     |
| <b>X</b>                      | : Don't care   |

| A2 | A1 | A0 | Voltage input to P6                       |
|----|----|----|---|
| 1  | 0  | 0  | 0.6V <sub>CC</sub> to 13.2V               |
| 0  | 1  | 1  | 0.45V <sub>CC</sub> to 0.6V <sub>CC</sub> |
| 0  | 1  | 0  | 0.3V <sub>CC</sub> to 0.45V <sub>CC</sub> |
| 0  | 0  | 1  | 0.15V <sub>CC</sub> to 0.3V <sub>CC</sub> |
| 0  | 0  | 0  | 0 to 0.15V <sub>CC</sub>                  |

Table 3 ADC levels

| MA1 | MA0 | Voltage input to P3                      |
|-----|-----|--|
| 0   | 0   | 0V to 0.2V <sub>CC</sub>                 |
| 0   | 1   | Always valid                             |
| 1   | 0   | 0.3V <sub>CC</sub> to 0.7V <sub>CC</sub> |
| 1   | 1   | 0.8V <sub>CC</sub> -13.2V                |

Table 4 Address selection

Fig. 3 Data formats

## APPLICATION

A typical application is shown in Fig. 4. All input/output interface circuits are shown in Fig. 6.

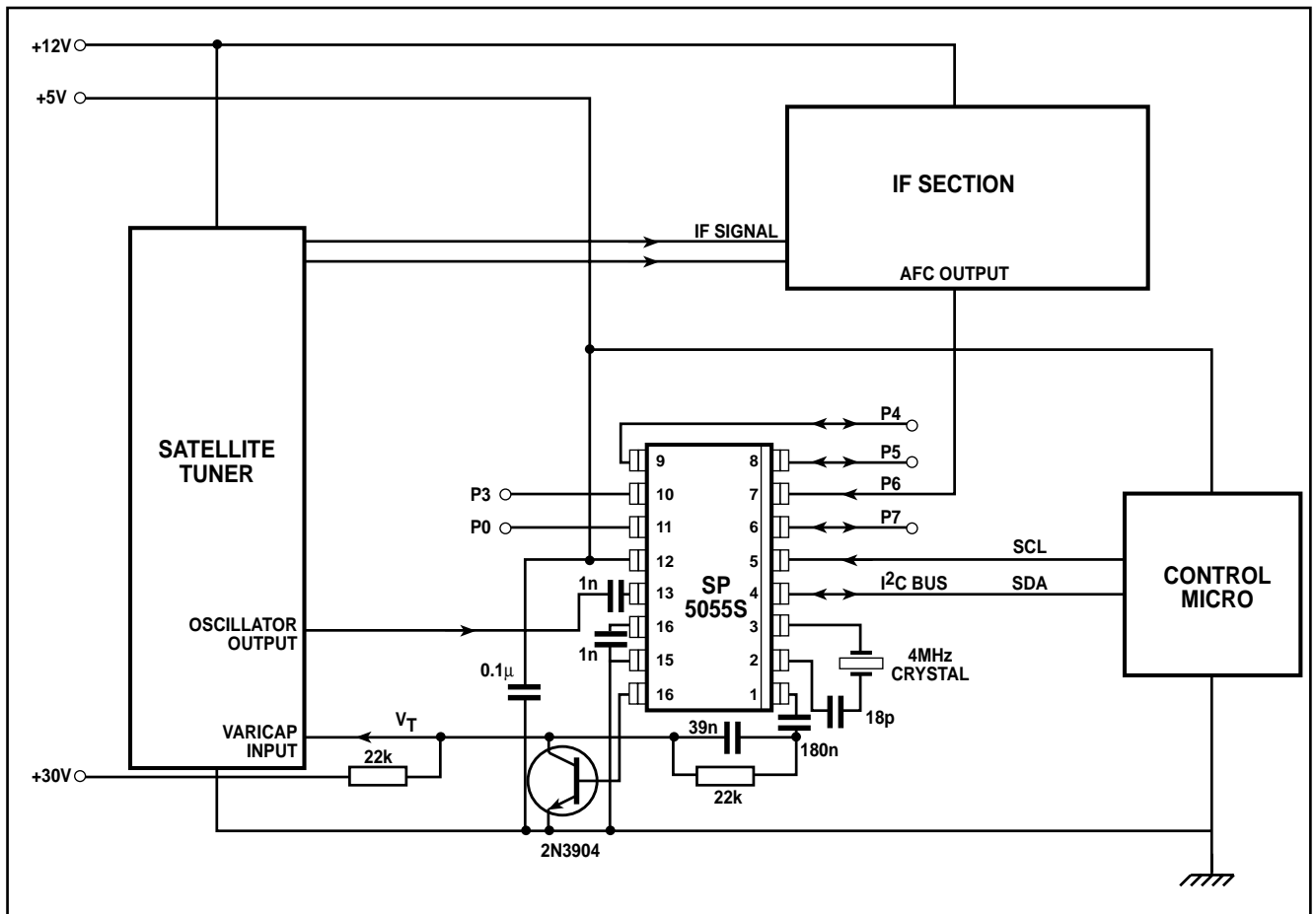


Fig. 4 Typical application

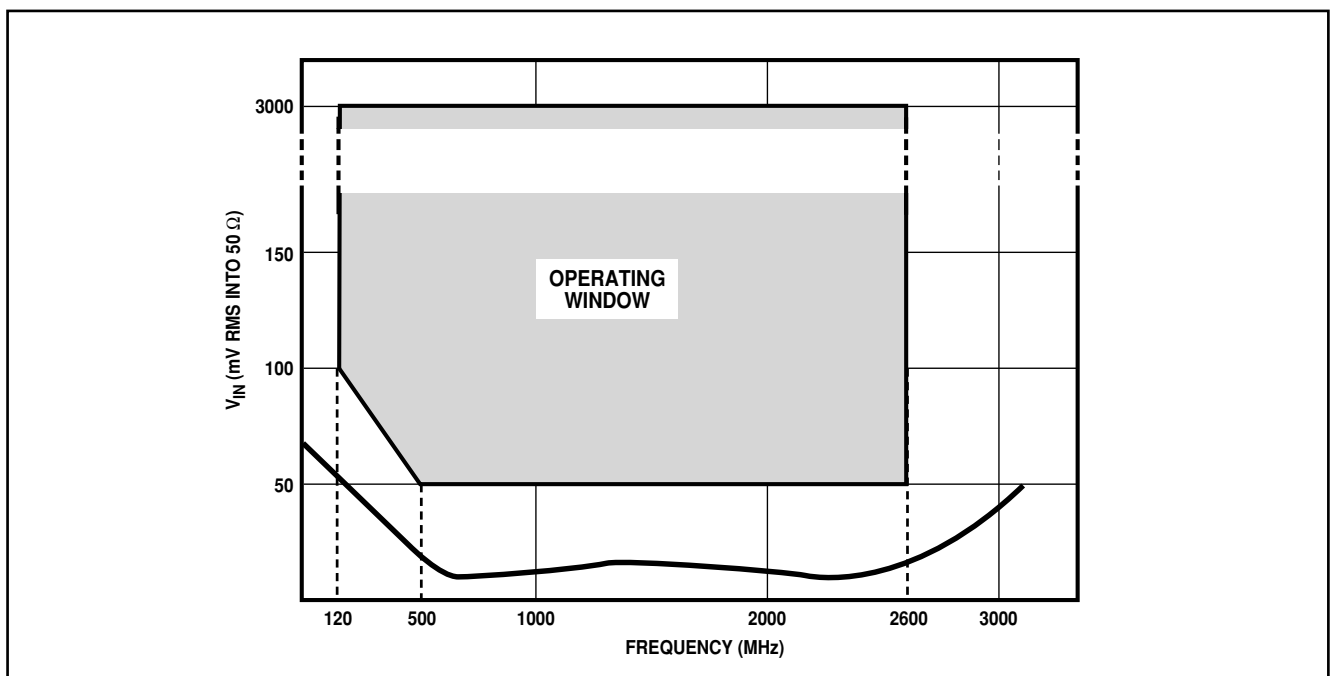


Fig. 5 Typical input sensitivity

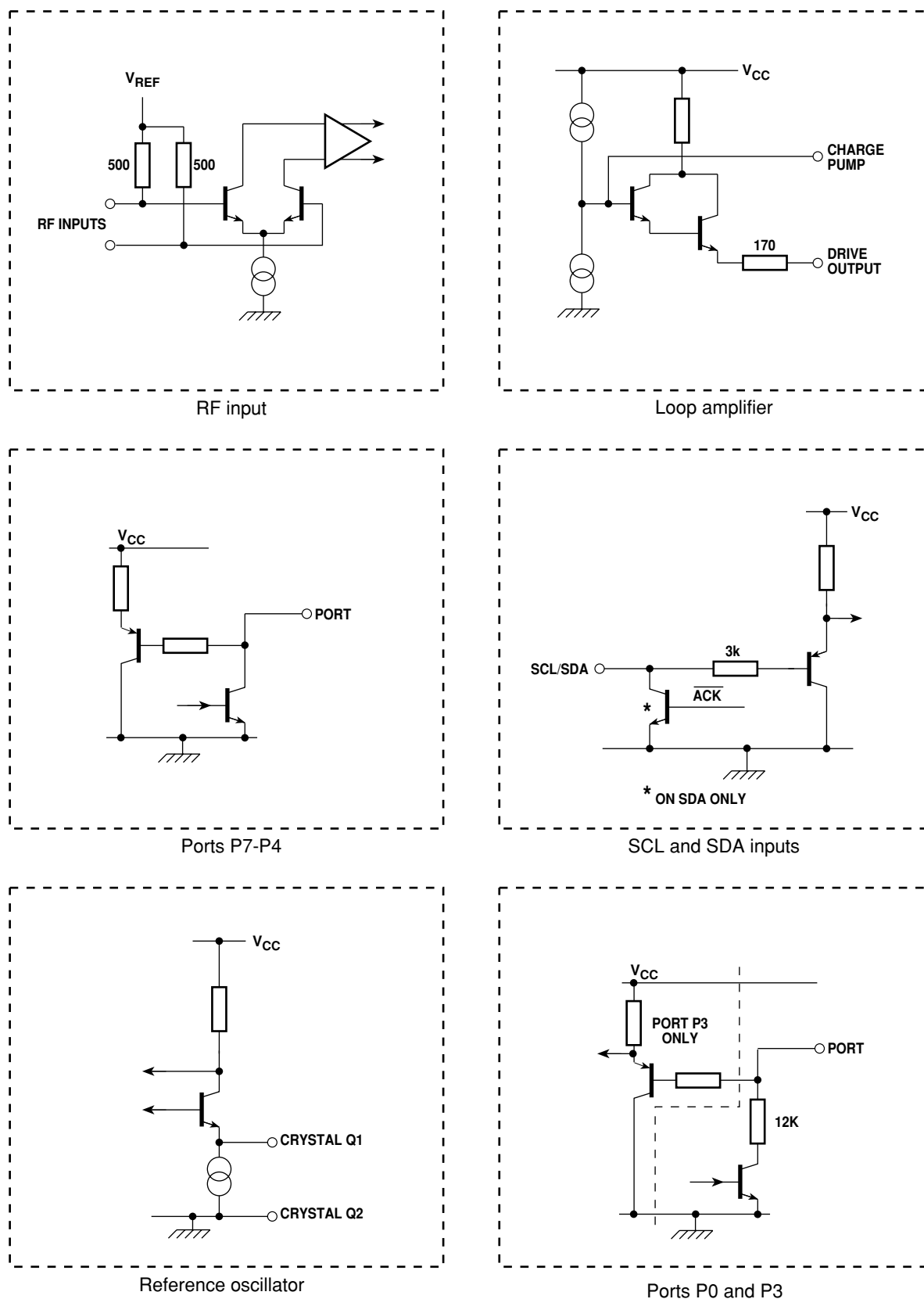


Fig. 6 SP5055 Input/output interface circuits

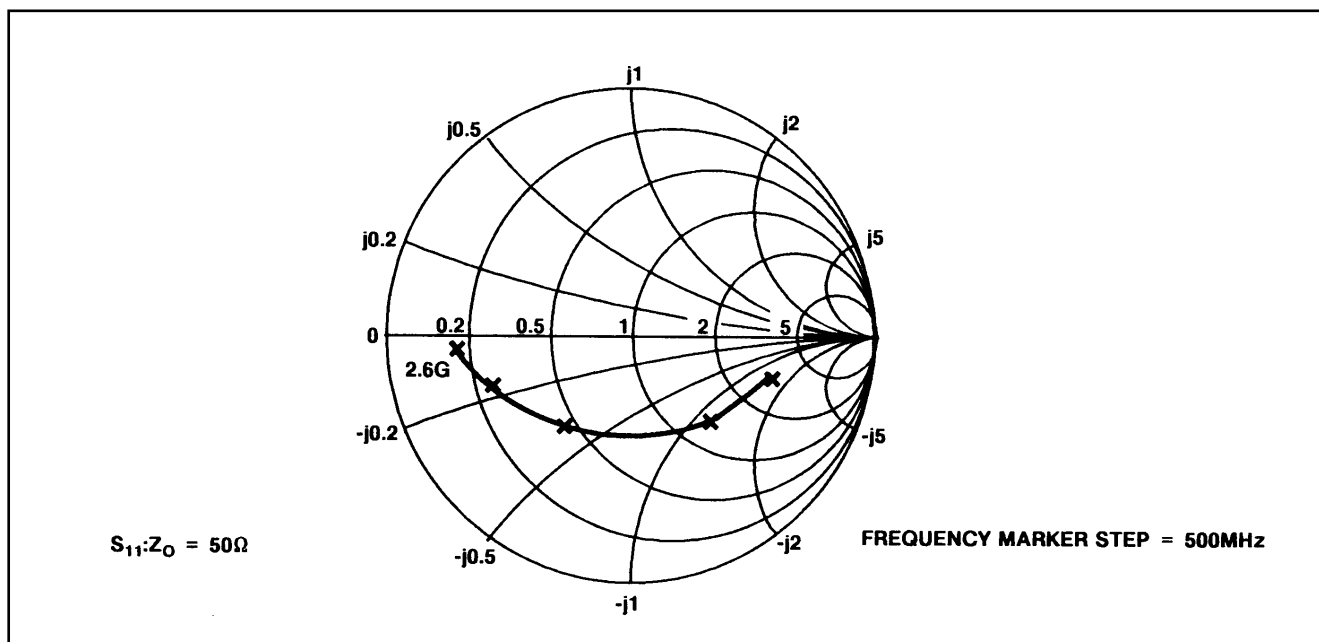
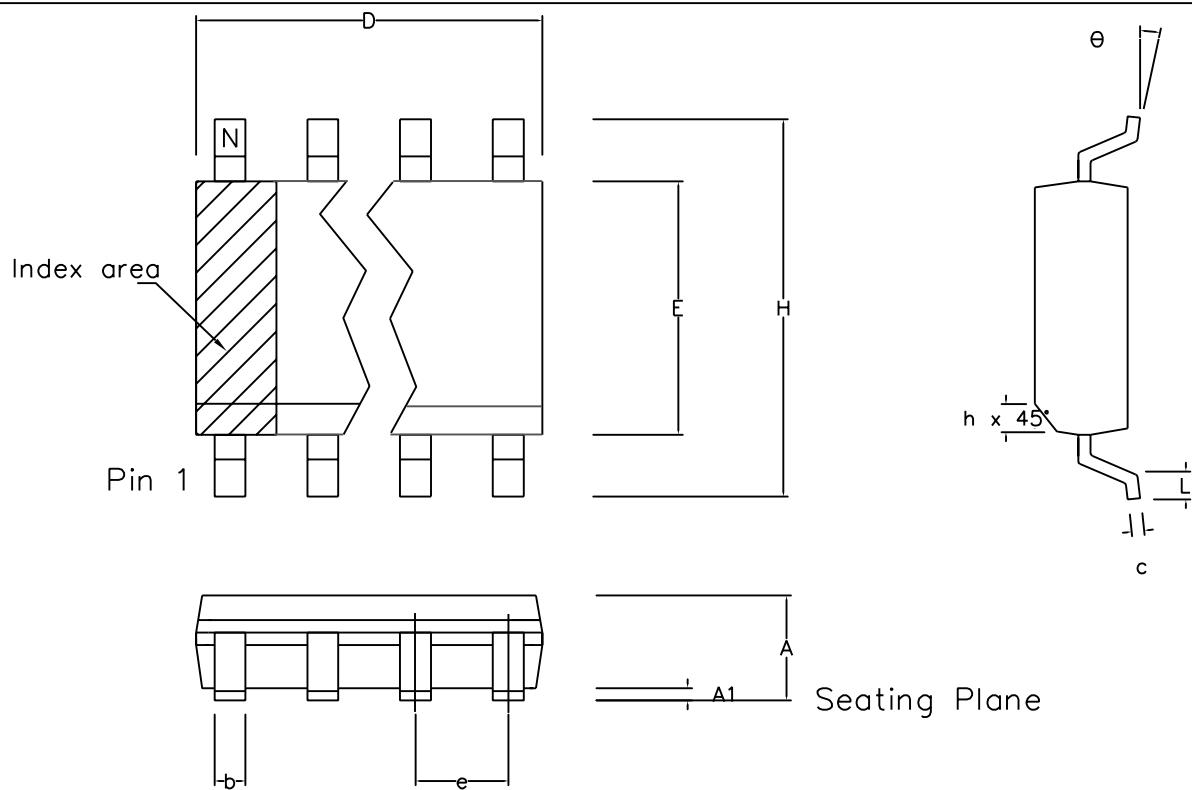


Fig. 7 Typical input impedance

**ABSOLUTE MAXIMUM RATINGS**All voltages are referred to  $V_{EE}$  and pin 3 at 0V

| Parameter                                 | Pin    | Value |              | Units | Conditions  |
|---|--------|-------|--------------|-------|---|
|   |        | Min.  | Max.         |       |   |
| Supply voltage                            | 12     | -0.3  | 7            | V     | Port in off state<br>Port in on state<br>Port in on state |
| RF input voltage                          | 13, 14 |       | 2.5          | Vp-p  |   |
| Port voltage                              | 6-11   | -0.3  | 14           | V     |   |
|   | 6-9    | -0.3  | 6            | V     |   |
|   | 10, 11 | -0.3  | 14           | V     |   |
| Total port output current                 | 6-11   |       | 50           | mA    | With $V_{CC}$ applied<br>$V_{CC}$ not applied             |
| RF input DC offset                        | 13, 14 | -0.3  | $V_{CC}+0.3$ | V     |   |
| Charge pump DC offset                     | 1      | -0.3  | $V_{CC}+0.3$ | V     |   |
| Drive DC offset                           | 16     | -0.3  | $V_{CC}+0.3$ | V     |   |
| Crystal oscillator DC offset              | 2      | -0.3  | $V_{CC}+0.3$ | V     |   |
| SDA, SCL input voltage                    | 4, 5   | -0.3  | $V_{CC}+0.3$ | V     |   |
|   |        | -0.3  | 5.5          | V     |   |
| Storage temperature                       |        | -55   | +125         | °C    |   |
| Junction temperature                      |        |       | +150         | °C    |   |
| MP 16 Thermal resistance, chip-to-ambient |        |       | 111          | °C/W  |   |
| MP 16 Thermal resistance, chip-to-case    |        |       | 41           | °C/W  |   |
| Power consumption at 5.5V                 |        |       | 440          | mW    | All ports off   |



|                                   | Min<br>mm    | Max<br>mm | Min<br>inch | Max<br>inch |
|-----------------------------------|--------------|-----------|-------------|-------------|
| A                                 | 1.35         | 1.75      | 0.053       | 0.069       |
| A1                                | 0.10         | 0.25      | 0.004       | 0.010       |
| D                                 | 9.80         | 10.00     | 0.386       | 0.394       |
| H                                 | 5.80         | 6.20      | 0.228       | 0.244       |
| E                                 | 3.80         | 4.00      | 0.150       | 0.157       |
| L                                 | 0.40         | 1.27      | 0.016       | 0.050       |
| e                                 | 1.27 BSC     |           | 0.050 BSC   |             |
| b                                 | 0.33         | 0.51      | 0.013       | 0.020       |
| c                                 | 0.19         | 0.25      | 0.008       | 0.010       |
| O                                 | 0°           | 8°        | 0°          | 8°          |
| h                                 | 0.25         | 0.50      | 0.010       | 0.020       |
|                                   | Pin Features |           |             |             |
| N                                 | 16           |           | 16          |             |
| Conforms to JEDEC MS-012AC Iss. C |              |           |             |             |

Notes:

1. The chamfer on the body is optional. If not present, a visual index feature, e.g. a dot, must be located within the cross-hatched area.
2. Controlling dimensions are in inches.
3. Dimension D do not include mould flash, protusion or gate burrs. These shall not exceed 0.006" per side.
4. Dimension E1 do not include inter-lead flash or protusion. These shall not exceed 0.010" per side.
5. Dimension b does not include dambar protusion / intrusion. Allowable dambar protusion shall be 0.004" total in excess of b dimension.

|   |        |         |         |        |         |                                  |  |
|---|--------|---------|---------|--------|---------|----------------------------------|--|
| © Zarlink Semiconductor 2002 All rights reserved. |        |         |         |        |         | Package Code DC                  |  |
| ISSUE   | 1      | 2       | 3       | 4      | 5       | Previous package codes<br>MP / S | Package Outline for<br>16 lead SOIC<br>(0.150" Body Width) |
| ACN   | 6745   | 201938  | 202597  | 203706 | 212431  |                                  |  |
| DATE  | 7Apr95 | 27Feb97 | 12Jun97 | 9Dec97 | 25Mar02 |                                  |  |
| APPRD.  |        |         |         |        |         |                                  | GPD00012   |







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